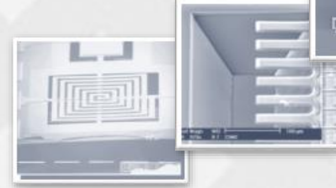
MEMS Prototyping



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In addition to SOI, BCD, CMOS, BiCMOS, SiGe and Silicon Photonic Integrated Circuits Integrated, bulk micromachining technologies and specific surface micromachining technologies are available through CMP.

CMP distributes Process Design-Kits (**PDK**) for CMOS/BiCMOS IC's, Photonic IC's and MEMS' technologies. Each of them contains technology files, simulation models, design rules, standard cell libraries. A copy of any requested design kit can be sent to the customer after a non-disclosure agreement (NDA) with CMP.
Customer request and support are provided through our Web interfaces:
Design-Kit Request Form-> **https://mycmp.fr/requests/design-kit-dk**
Design-Kit Support Center: **https://mycmp.fr/requests/support**

Contact us
Request Form: S. EYRAUD [Sylvaine.Eyraud@mycmp.fr]
Support Center: Ch. RABACHE [Christelle.Rabache@mycmp.fr]

ams 0.35µm CMOS Bulk Micromachining

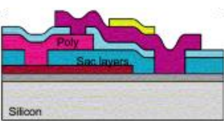
Front-side
Bulk Micromachining
Suspended Beams

Based on standard ams CMOS or BiCMOS process, this technology allows integration of MEMS sensor and front-end electronic on the same die for integration and better signal to noise ratio. Suspended passive devices or structures can be made with this technology. Applications include thermal, inertial and infrared sensors.
ams 0.35µm CMOS Bulk Micromachining:
Front-side or Back-side

MEMSCAP: PolyMUMPS -SOIMUMPS - PiezoMUMPS

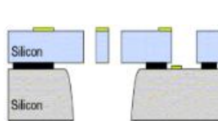
Allows the realization of various MEMS devices

PolyMUMPS



Polysilicon/gold surface micromachining

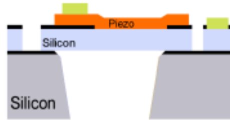
SOIMUMPS



SoiMUMPs_SEM view

Deep reactive ion etching on silicon on insulator

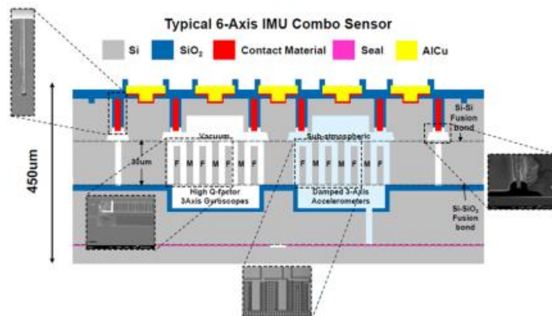
PiezoMUMPS



On-chip suspended membrane with piezoresistors

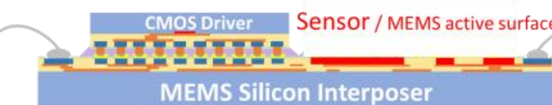
SOIMUMPS + piezoelectric layer

Teledyne DALSA TDSI MIDIS ™



MIDIS™ MEMS technology is offered to CMP user community thanks to an agreement and partnership with CMC, Canada. The MEMS Integrated Design for Inertial Sensors (MIDIS™) platform is designed to provide a standard process for manufacturing accelerometers and gyroscopes

Packaging



Optical resin
Chip On Board (COB)
Thermal solutions
Metallic package
Hermetic sealing
Hybrid packaging MEMS /Si Photonics + CMOS

- Digressive prices are applied to most MPW services.
- Prices on the Web site.

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Partnership:

Sept-19